Tool ID: 224
Tool Location: 111

## Equipment Information Sheet

# Oxford Cobra ICP Dielectric

**Manager:** **Jeremy Clark** **607-254-6487**
**Backup:** **Philip Schneider** **607-254-4931**

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

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**SAFETY**
**USAGE RESTRICTIONS**
**SCHEDULING/SIGN-UP RESTRICTIONS**
**MATERIALS COMPATIBILITY CATEGORY**

*Minimum Tool Time: 15 minutes*

### Tool Category 1E: Silicon Based Materials and Select Dieletrics

| Allowed | Not Allowed |
|---|---|
| Silicon Based Materials only | No Evaporated or Sputtered Films |
| Si, SiC, $SiO_2$ substrates | No Metal or Organic Films |
| All Furnace grown or deposited films | No Glass Substrates |
| PECVD Films | No III/V Compound Semiconductors |
| Select ALD dieletrics ($SiO_2$, SiN, $HfO_2$, HFN) | No High Vapor pressure materials |
| Spin on Glass and Spin on Dopants | Organic/Biology Molecules prepared-with or without Salt buffers |

**High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.**

### Additional Material Restrictions and Exceptions

- No metals allowed
- 100mm wafers only
- 5mm of resist must be removed from the edge of the wafer.
- Pieces may be temporarily bonded to a carrier wafer with Cool Grease

*Last Updated: 06/23/2026*